

FSC-BT909

4.2 Dual Mode Bluetooth Module Data Sheet

(Class 11)

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Release Record

| Version Number | Release Date | Comments |
|----------------|--------------|---|
| Revision 1.0 | 2016-12-08 | First Release |
| Revision 1.1 | 2017-08-12 | 1, Modify the block diagram and some incorrect descriptions 2, Increase I2S application circuit diagram 3, Add FCC, CE, ROHS certificate number |
| Revision 1.2 | 2019-02-20 | Bluetooth version updated to V4.2 |
| Revision 1.3 | 2019-09-02 | Remove the ROHS certificate |
| Revision 1.4 | 2019-10-18 | Feature update |
| Revision 1.5 | 2020-04-30 | Increase power consumption parameters |
| Revision 1.6 | 2021-01-27 | Update model by applying circuit diagram codec |
| Revision 1.7 | 2024-05-06 | Modify the working temperature to -30~85°C |

1. INTRODUCTION

FSC-BT909 is a bluetooth 4.2 Smart Ready device (with BR/EDR & LE support simultaneously) . It is a small form factor, highly power and highly economic Bluetooth radio module that allows OEM to add wireless capability to their products. The module supports multiple interfaces that make it simple to integrate into fully certified embedded Bluetooth solutions.

With Feasycom's Bluetooth stack running on a host, designers can easily customize their applications to support different Bluetooth profiles, such GATT, OPP, DUN, SPP, and etc. The module supports Bluetooth® Enhanced Data Rate (EDR) and delivers up to 3 Mbps data rate for distances to 100M.

The module is an appropriate product for designers who want to add wireless capability to their products. The supported remote devices' OS are iOS, Android, and Windows.

External whip antenna, transmitting over 2000M.

1.1 Block Diagram

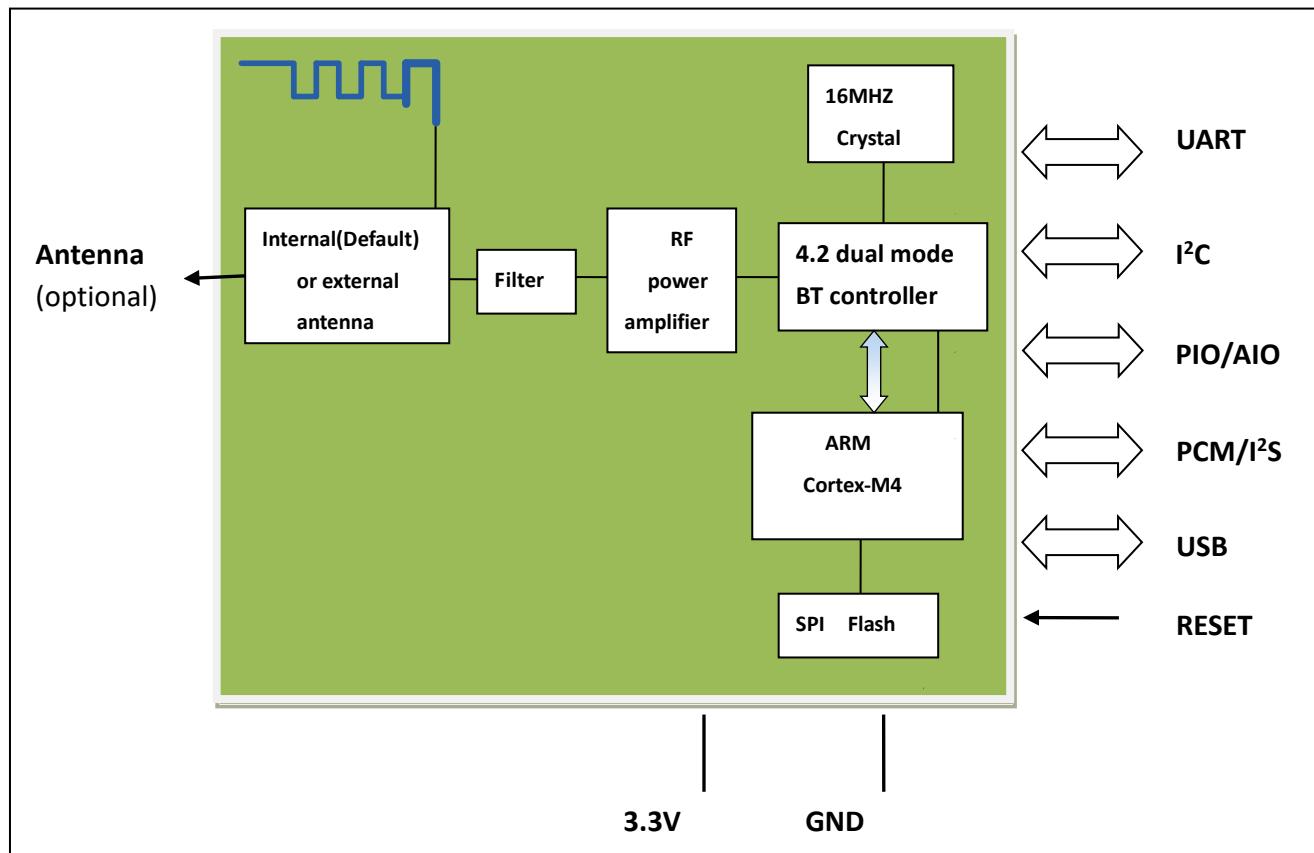


Figure 1-1-1

1.2 Feature

- ◆ Fully qualified Bluetooth 4.2/3.0/2.1/2.0/1.2/1.1
- ◆ Postage stamp sized form factor.
- ◆ Class 1 support (high output power).
- ◆ Integrated chip antenna, transmitting over 100m.
- ◆ The default UART Baud rate is 115.2Kbps and can support from 1200bps up to 921Kbps.
- ◆ UART, I²C , PCM/I²S data connection interfaces.
- ◆ Profiles including GATT, OPP, DUN, SPP, etc..
- ◆ USB 2.0 full-speed device/host/OTG controller.
- ◆ RoHS compliant.
- ◆ FCC, CE Certified.
- ◆ Power Consumption In Sleep Mode (VDD_3V3 at 3.3 V)
 - Discoverable: 1.73mA
 - BR/EDR Connection: 11.12mA
 - LE Connection: 2.46mA
- ◆ Power Consumption In Working Mode (VDD_3V3 at 3.3 V)
 - Discoverable: 11.56mA
 - BR/EDR Connection: 20.95mA
 - LE Connection: 12.08mA

1.3 Application

- ◆ Cable replacement
- ◆ Point-of-sales systems
- ◆ Barcode readers and pay terminals
- ◆ Telemetry devices
- ◆ Automotive inspection and measurement systems
- ◆ Industrial devices
- ◆ Barcode and RFID scanners
- ◆ Wireless speakers
- ◆ Analogue and USB Multimedia Dongles

2. GENERAL SPECIFICATION

Table 2-1:

| General Specification | |
|-------------------------|---|
| Chipset | BT4.2 Dual Mode |
| Product ID | FSC-BT909 |
| Dimension | 13mm(W) x 26.9mm(L) x 2.4mm(H) (Tolerance: ±0.1mm) |
| Bluetooth Specification | Bluetooth V4.2 (Dual Mode) |
| Power Supply | 3.3 Volt DC |
| Output Power | 18.5 dBm (Class 1) |
| Sensitivity | -86dBm@0.1%BER |
| Frequency Band | 2.402GHz -2.480GHz ISM band |
| Modulation | 8DPSK,DQPSK |
| Baseband Crystal OSC | 16MHz |
| Hopping & channels | 1600hops/sec, 1MHz channel space, 79 Channels(BT 4.2 to 2MHz channel space) |
| RF Input Impedance | 50 ohms |
| Antenna | Multilayer Ceramic Antenna (Set aside an external antenna interface) |
| Interface | Data: UART (Standard), I ² C Audio: PCM/I ² S Others: PIO, AIO, Touch sensor, PWM. USB 2.0 |
| Profile | SPP, GATT(BLE Standard) Airsync, ANCS, iBeacon, HID |
| Temperature | -30°C to +85°C |
| Humidity | 10%~95% Non-Condensing |
| Environmental | RoHS Compliant |
| MSL grade: | MSL 3 |
| ESD grade | Human Body Model: Class-2 Machine Model: Class-B |

3. PHYSICAL CHARACTERISTIC

- Dimension : 13mm(W) x 26.9mm(L) x 2.4mm(H) Tolerance: $\pm 0.1\text{mm}$
- Module size: 13mm X 26.9mm Tolerance: $\pm 0.2\text{mm}$
- Pad size: 1mmX0.8mm Tolerance: $\pm 0.2\text{mm}$
- Pad pitch: 1.5mm Tolerance: $\pm 0.1\text{mm}$

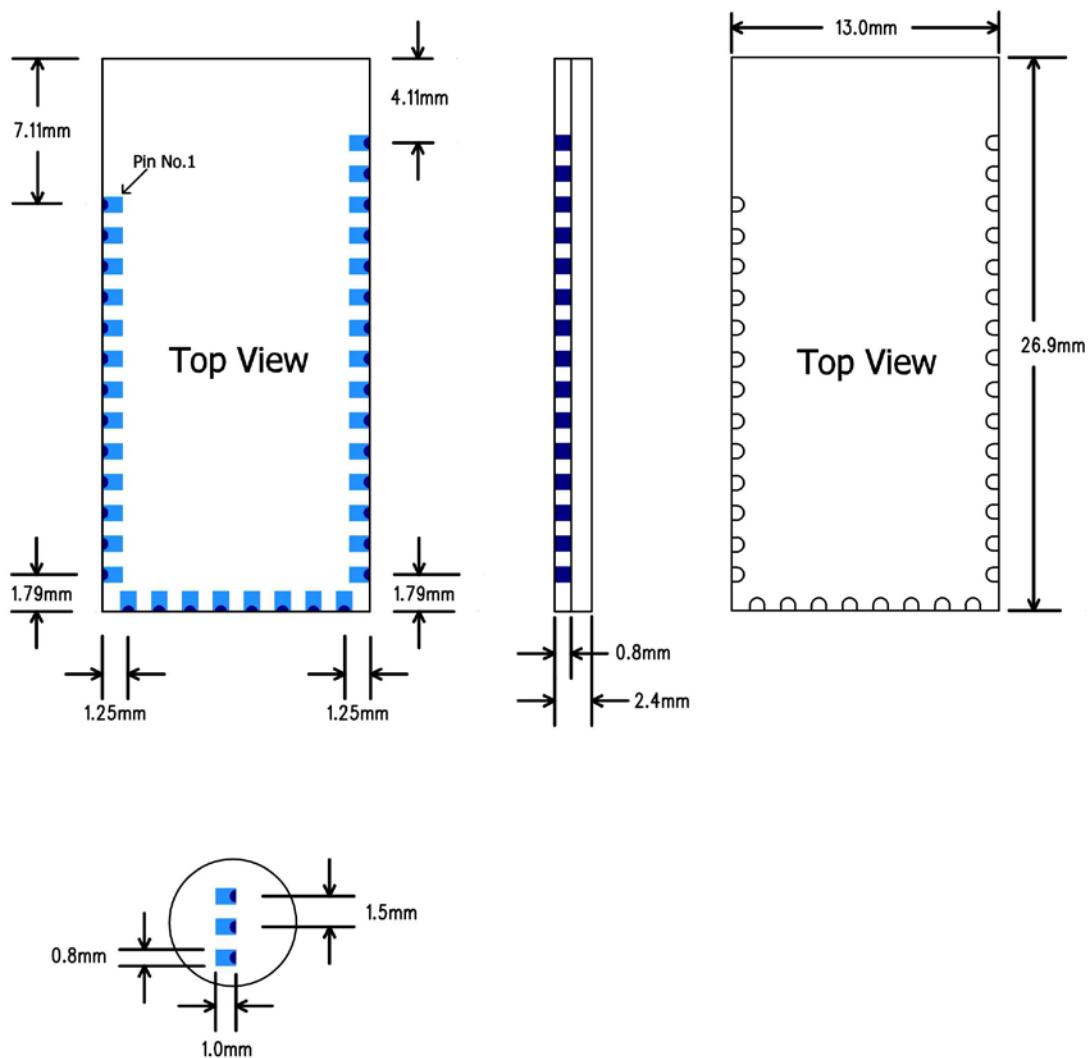


Figure 3-1

4. PIN DEFINITION DESCRIPTIONS

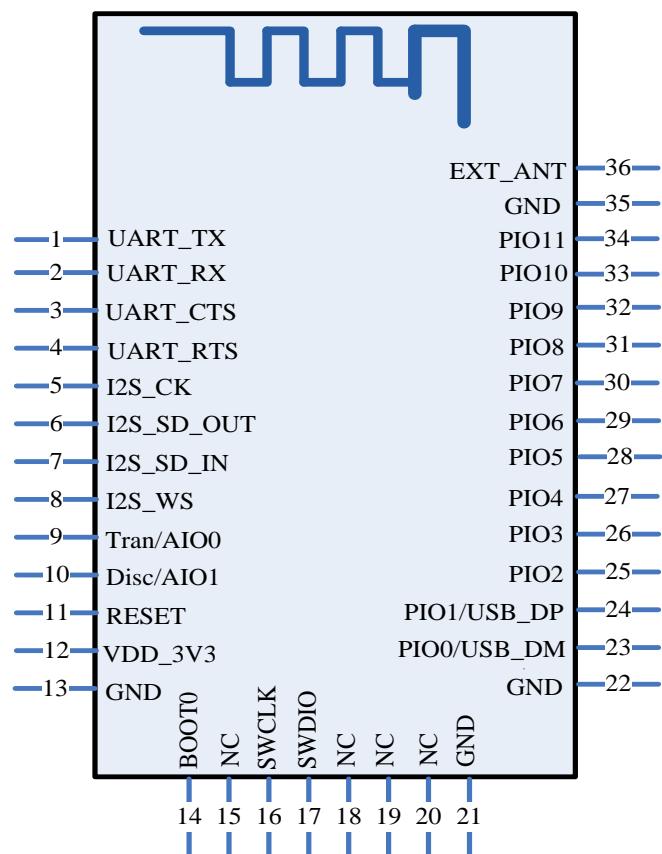


Figure 4-1: FSC-BT909 PIN Diagram

Table 4-1:

| Pin NO. | Pin Name | Type | Pin Descriptions |
|---------|------------|--------------------------------|---|
| 1 | UART_TX | CMOS output | UART data output |
| 2 | UART_RX | CMOS input | UART data input |
| 3 | UART_CTS | CMOS input | UART clear to send active low |
| | | Bi-directional | Alternative Function: Programmable input/output line |
| 4 | UART_RTS | CMOS output/ Bi-directional | UART request to send active low |
| | | Bi-directional | Alternative Function: Programmable input/output line |
| 5 | I2S_CK | Bi-directional | I ² S CLK (BCLK) |
| 6 | I2S_SD_OUT | Bi-directional | I ² S Data Output |
| 7 | I2S_SD_IN | Bi-directional | I ² S Data Input |
| 8 | I2S_WS | Bi-directional | I ² S Chip Select For Synchronous Serial Interface |
| 9 | Tran/AIO0 | I/O | Programmable input/output line |
| | | | Alternative Function 1: Analogue programmable I/O line. Alternative Function 2: Host MCU change UART transmission mode. |
| 10 | Disc/AIO1 | | |
| 11 | RESET | | |
| 12 | VDD_3V3 | | |
| 13 | GND | | |
| 14 | BOOT0 | NC | |
| 15 | | SWCLK | |
| 16 | | SWDIO | |
| 17 | | NC | |
| 18 | | NC | |
| 19 | | NC | |
| 20 | | NC | |
| 21 | | GND | |

| | | | |
|----|-------------|----------------|---|
| 10 | Disc/AIO1 | I/O | Programmable input/output line Alternative Function 1: Analogue programmable I/O line. Alternative Function 2: Host MCU disconnect bluetooth. |
| 11 | RESET | CMOS input | Reset if low. Input debounced so must be low for >5ms to cause a reset. |
| 12 | VDD_3V3 | VDD | Power supply voltage 3.3V |
| 13 | GND | VSS | Power Ground |
| 14 | BOOT0 | CMOS input | The default is low. (internal 10K resistance drop) When writing to MCU when using the serial port, this pin is connected with the high level. |
| 15 | NC | NC | NC |
| 16 | SWCLK | Bi-directional | Debugging through the clk line(Default) |
| 17 | SWDIO | Bi-directional | Debugging through the data line(Default) |
| 18 | NC | NC | NC |
| 19 | NC | NC | NC |
| 20 | NC | NC | NC |
| 21 | GND | VSS | Power Ground |
| 22 | GND | VSS | Power Ground |
| 23 | PIO0/USB_DM | Bi-directional | Programmable input/output line Alternative Function: USB_DM |
| 24 | PIO1/USB_DP | Bi-directional | Programmable input/output line Alternative Function: USB_DP |
| 25 | PIO2 | Bi-directional | Programmable input/output line |
| 26 | PIO3 | Bi-directional | Programmable input/output line |
| 27 | PIO4 | Bi-directional | Programmable input/output line |
| 28 | PIO5 | Bi-directional | Programmable input/output line |
| 29 | PIO6 | Bi-directional | Programmable input/output line Alternative Function: I ² C Serial Clock input/output |
| 30 | PIO7 | Bi-directional | Programmable input/output line Alternative Function: I ² C Serial Data input/output |
| 31 | PIO8 | Bi-directional | Programmable input/output line |
| 32 | PIO9 | Bi-directional | Programmable input/output line Alternative Function: LED(Default) |

| | | | |
|----|---------|------------------|---|
| 33 | PIO10 | Bi-directional | Programmable input/output line Alternative Function: BT Status(Default) |
| 34 | PIO11 | Bi-directional | Programmable input/output line |
| 35 | GND | VSS | Power Ground |
| 36 | EXT_ANT | RF signal output | By default, this PIN is an empty feet. This PIN can connect to an external antenna to improve the Bluetooth signal coverage. If you need to use an external antenna, by modifying the module on the OR resistance to block out the on-board antenna; Or contact Feasycom for modification. |

5. Electrical Characteristics

5.1 Absolute Maximum Ratings

The module should not continuously run under extreme conditions. The absolute maximum ratings are summarized in Table below. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability and cause permanent damage to the device.

Table 5-1-1:

| Temperature/Voltage | Min | Max | Unit |
|-----------------------|-----------|-----------|------|
| Storage temperature | -40 | 85 | °C |
| Operating temperature | -30 | 85 | °C |
| Supply voltage | -0.3 | 3.6 | V |
| Terminal voltages | VSS - 0.4 | Vdd + 0.4 | V |

5.2 Recommended Operating Conditions

The recommended operating conditions are summarized in Table below..FSC-BT909 operates as low as 2.7 V supply voltage. However, to safely meet the USBspecification for minimum voltage for USB data lines, minimum of 3.1 V supply is required

Table 5-2-1:

| Temperature/Voltage | Min | Typ | Max | Unit |
|-----------------------|-----|-----|-----|------|
| Operating temperature | -30 | 20 | 85 | °C |
| Supply voltage | 2.7 | 3.3 | 3.6 | V |
| Terminal voltages | 0 | | Vdd | V |

5.3 Terminal Characteristics

FSC-BT909's terminal characteristics are summarized Table below.

Table 5-3-1:

| Characteristics | Min | Typ | Max | Unit |
|--|--------------------|---------------------|--------|------|
| I/O static characteristics | | | | |
| VIL input logic level low | - | - | 0.3VDD | V |
| VIH input logic level high | 0.4V _{DD} | - | - | V |
| VHYS input hysteresis | - | 10% V _{DD} | - | V |
| Ilkg input leakage current | - | - | 1 | uA |
| RPU Weak pull-up equivalent resistor | 30 | 40 | 50 | kΩ |
| RPD Weak pull-down equivalent resistor | 30 | 40 | 50 | kΩ |
| CIO pin capacitance | - | 5 | - | pF |
| VOL output logic level low | - | - | 0,2 | V |
| VOH output logic level high | Vdd -0.4 | - | - | V |
| NRST pin characteristics | | | | |
| VTH,res threshold voltage | 1.65 | 1.8 | VDD | V |
| Rires input resistance | - | 10 | - | kΩ |
| Cires input capacitance | - | 100 | - | nF |

5.4 Current Consumption

FSC-BT909's current consumption is summarized in Table below.

Table 5-4-1:

| Operation Mode | Connection Type | Average | Unit |
|-----------------|--|---------|------|
| Standby | -- | 150 | uA |
| Discoverable | Inquiry/page:640mS interval ,11.25mS window Advertising :152.5mS interval | 28 | mA |
| ACL Connection | Active Mode | 34 | mA |
| | File transfer ,throughput | 44 | mA |
| LE Connection | 20mS Interval | 30 | uA |
| | File transfer ,throughput | 36 | mA |
| Maximum Current | Send 2441MHZ fixed frequency signals | ~225 | mA |

5.5 Radio Characteristics

5.5.1 Transmitter Radio Characteristics

TX output is guaranteed to be unconditionally stable over the guaranteed temperature range.

Refer to Table below. Measurement conditions: T = 20 °C, Vdd = 3.3V.

Table 5-5-1-1:

| Item | Typical Value | Bluetooth Specification | Unit |
|--|---------------|-------------------------------|----------------|
| Maximum output power1,2 | +18.5 | -6 to 20 | dBm |
| RF power control range | 34 | ≥ 16 | dB |
| 20dB bandwidth for modulated carrier | 790 | ≤ 1000 | kHz |
| Adjacent channel transmit power $F = F_0 \pm 2\text{MHz}$ | -36 | ≤ 20 | dBm |
| Adjacent channel transmit power $F = F_0 \pm 3\text{MHz}$ | -45 | $\square -40$ | dBm |
| Adjacent channel transmit power $F = F_0 \pm > 3\text{MHz}$ | -50 | $\square -40$ | dBm |
| $\square \Delta f_{1\text{avg}}$ Maximum Modulation | 168 | $140 < f_{1\text{avg}} < 175$ | kHz |
| $\square \Delta f_{2\text{max}}$ Maximum Modulation | 152 | 115 | kHz |
| $\square \Delta f_{1\text{avg}} / \Delta f_{2\text{avg}}$ | 0.94 | $\square \square \geq 0.80$ | - |
| Initial carrier frequency tolerance | 15 | $\square \leq 75$ | kHz |
| Drift Rate | 8 | $\square \leq 20$ | kHz/50 μ s |
| Drift (single slot packet) | 7 | $\square \leq 25$ | kHz |
| Drift (five slot packet) | 9 | $\square \leq 40$ | kHz |
| 2nd Harmonic content | -65 | $\square \leq -30$ | dBm |
| 3rd Harmonic content | -45 | $\square \leq -30$ | dBm |

5.5.2 Receiver Radio Characteristics

RX input is guaranteed to be unconditionally stable over the guaranteed temperaturerange. Refer to Table below. Measurement conditions: $T = 20^\circ\text{C}$, $V_{dd} = 3.3\text{V}$.

Table 5-5-2-1:

| | Frequency(GHz) | Typ. | Unit | Bluetooth Specification |
|--|----------------|------|------|-------------------------|
| Sensitivity@0.1% BER for all packet types | 2.402 | -85 | dBm | <-75dBm |
| | 2.441 | -86 | dBm | |
| | 2.480 | -85 | dBm | |
| BER@ Maximum received signal(-20dBm) | 2.402 | 0 | dBm | <0.1% |
| | 2.441 | 0 | dBm | |
| | 2.480 | 0 | dBm | |

6. Interface Characteristics

6.1 UART Interface

Four signals are used to implement the UART function. When FSC-BT909 is connected to another digital device, **UART_RX** and **UART_TX** transfer data between the two devices. The remaining two

signals, UART_CTS and UART_RTS, can be used to implement RS232 hardware flow control where both are active low indicators.

Table 6-1-1:The interface consists of four-line connection as described in below:

| Signal name | Driving source | Description |
|-------------|------------------|--|
| UART-TX | FSC-BT909 module | Data from FSC-BT909 module |
| UART-RX | Host | Data from Host |
| UART-RTS | FSC-BT909 module | Request to send output of FSC-BT909 module |
| UART-CTS | Host | Clear to send input of FSC-BT909 module |

Table 6-1-2:Possible UART Settings

| Property | Possible Values |
|---------------------|--------------------|
| Baud Rate | 1200bps to 921Kbps |
| Flow Control | RTS/CTS or None |
| Data bit length | 8bits |
| Parity | None, Odd or Even |
| Number of Stop Bits | 1 or 2 |

Table 6-1-3:Default Data Format

| Property | Possible Values |
|---------------------|-----------------|
| Baud Rate | 115.2Kbps |
| Flow Control | None |
| Data bit length | 8bit |
| Parity | None |
| Number of Stop Bits | 1 |

6.2 PCM/I²S Interface

The I²S can be operated in master or slave mode, in full duplex and simplex communication modes and can be configured to operate with a 16-/32-bit resolution as an input or output channel. Audio sampling frequencies from 8 kHz up to 192 kHz are supported. When either or both of the I²S interfaces is/are configured in master mode, the master clock can be output to the external DAC/CODEC at 256 times the sampling frequency.

The I²S can be served by the DMA controller.

6.2.1 I²S dynamic characteristics

Table 6-2-1-1: I²S dynamic characteristics

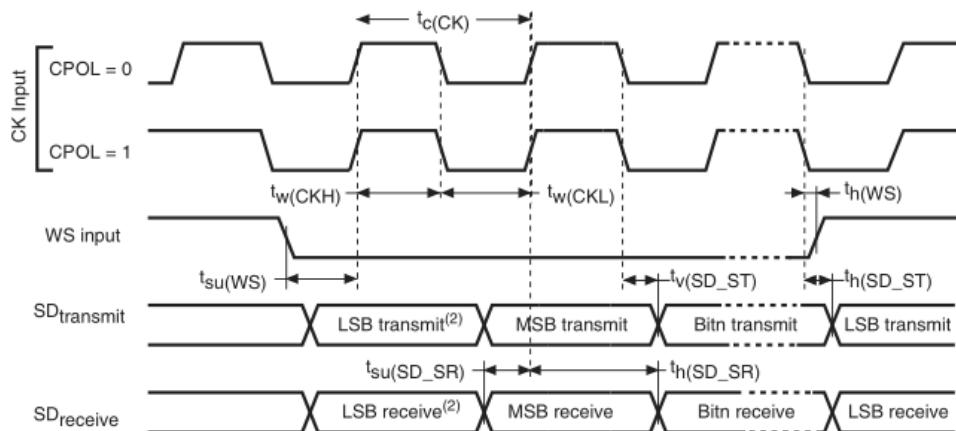
| Symbol | Parameter | Conditions | Min | Max | Unit |
|------------------|---|--|--------|------------------|------|
| f_{MCK} | I ² S Main clock output | - | 256x8K | 256x $F_s^{(2)}$ | MHz |
| f_{CK} | I ² S clock frequency | Master data: 32 bits | - | 64 F_s | MHz |
| | | Slave data: 32 bits | - | 64 F_s | |
| D_{CK} | I ² S clock frequency duty cycle | Slave receiver | 30 | 70 | % |
| $t_{v(WS)}$ | WS valid time | Master mode | 0 | 6 | ns |
| $t_{h(WS)}$ | WS hold time | Master mode | 0 | - | |
| $t_{su(WS)}$ | WS setup time | Slave mode | 1 | - | |
| $t_{h(WS)}$ | WS hold time | Slave mode | 0 | - | |
| $t_{su(SD_MR)}$ | Data input setup time | Master receiver | 7.5 | - | |
| $t_{su(SD_SR)}$ | | Slave receiver | 2 | - | |
| $t_{h(SD_MR)}$ | Data input hold time | Master receiver | 0 | - | |
| $t_{h(SD_SR)}$ | | Slave receiver | 0 | - | |
| $t_{v(SD_ST)}$ | Data output valid time | Slave transmitter (after enable edge) | - | 27 | |
| $t_{h(SD_ST)}$ | | Master transmitter (after enable edge) | - | 20 | |
| $t_{v(SD_MT)}$ | Data output hold time | Master transmitter (after enable edge) | 2.5 | - | |
| $t_{h(SD_MT)}$ | | Master transmitter (after enable edge) | 2.5 | - | |

1. Guaranteed by characterization.

2. The maximum value of 256 F_s is 42 MHz (APB1 maximum frequency).

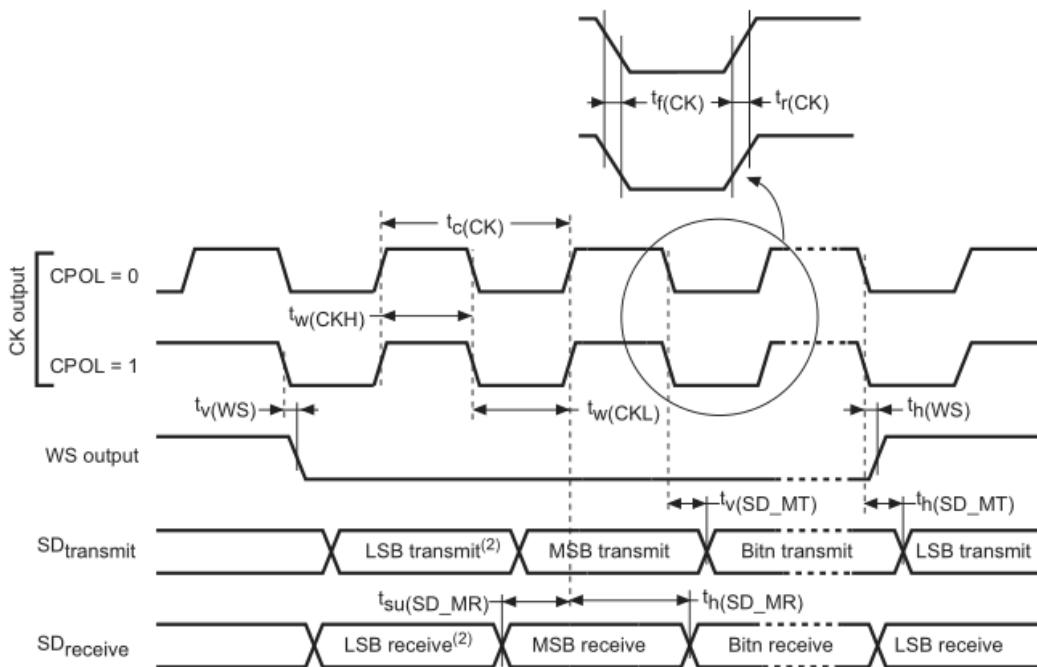
Note: Refer to the I²S section of the reference manual for more details on the sampling frequency(F_s).

f_{MCK} , f_{CK} , and D_{CK} values reflect only the digital peripheral behavior. The values of these parameters might be slightly impacted by the source clock precision. D_{CK} depends mainly on the value of ODD bit. The digital contribution leads to a minimum value of (I2SDIV/(2*I2SDIV+ODD) and a maximum value of (I2SDIV+ODD)/(2*I2SDIV+ODD). F_s maximum value is supported for each mode/condition.



1. LSB transmit/receive of the previously transmitted byte. No LSB transmit/receive is sent before the first byte.

Figure 6-2-1-1: I²S slave timing diagram (Philips protocol)



1. LSB transmit/receive of the previously transmitted byte. No LSB transmit/receive is sent before the first byte.

Figure 6-2-1-2: I²S master timing diagram (Philips protocol)

6.3 AIO , PIO lines and I²C

Up to 16 programmable bidirectional input/output (I/O) can be used.

Two general purpose analogue interface pin can be used.

PIO6 and PIO7 can be used as I²C interface.

Inter-Integrated Circuit Interface (I²C)

I²C bus interfaces can operate in multi-master and slave modes. They can support the standard (up to 100 kHz) and fast (up to 400 kHz) modes. The I²C bus frequency can be increased up to 1 MHz. For more details about the complete solution, please contact your local ST sales representative. They also support the 7/10-bit addressing mode and the 7-bit dual addressing mode (as slave). A hardware CRC generation/verification is embedded.

They can be served by DMA and they support SMBus 2.0/PMBus.

The devices also include programmable analog and digital noise filters

Analog to Digital Converter (ADC)

One 12-bit analog-to-digital converter is embedded and shares up to 16 external channels, performing conversions in the single-shot or scan mode. In scan mode, automatic conversion is performed on a selected group of analog inputs.

The ADC can be served by the DMA controller. An analog watchdog feature allows very precise monitoring of the converted voltage of one, some or all selected channels. An interrupt is generated when the converted voltage is outside the programmed thresholds.

To synchronize A/D conversion and timers, the ADCs could be triggered by any of TIM1, TIM2, TIM3, TIM4 or TIM5 timer.

6.4 USB Interface

USB 2.0 full-speed device/host/OTG controller with on-BT Module PHY.

Table 6-4-1: USB OTG FS startup time

| Symbol | Parameter | Max | Unit |
|---------------------|-------------------------------------|-----|---------|
| $t_{STARTUP}^{(1)}$ | USB OTG FS transceiver startup time | 1 | μs |

1. Guaranteed by design.

Table 6-4-2: USB OTG FS DC electrical characteristics

| Symbol | Parameter | Conditions | Min. ⁽¹⁾ | Typ. | Max. ⁽¹⁾ | Unit |
|---------------|--------------------------|---------------------------------|---|------|---------------------|------------|
| Input levels | V_{DD} | USB OTG FS operating voltage | 3.0 ⁽²⁾ | - | 3.6 | V |
| | $V_{DI}^{(3)}$ | Differential input sensitivity | I(USB_FS_DM/DP) | 0.2 | - | - |
| | $V_{CM}^{(3)}$ | Differential common mode range | Includes V_{DI} range | 0.8 | - | 2.5 |
| | $V_{SE}^{(3)}$ | Single ended receiver threshold | | 1.3 | - | 2.0 |
| Output levels | V_{OL} | Static output level low | R_L of 1.5 k Ω to 3.6 V ⁽⁴⁾ | - | - | 0.3 |
| | V_{OH} | Static output level high | R_L of 15 k Ω to $V_{SS}^{(4)}$ | 2.8 | - | 3.6 |
| R_{PD} | PIO0,PIO1 (USB_FS_DM/DP) | $V_{IN} = V_{DD}$ | 17 | 21 | 24 | k Ω |
| R_{PU} | PIO0,PIO1 (USB_FS_DM/DP) | $V_{IN} = V_{SS}$ | 1.5 | 1.8 | 2.1 | |

1. All the voltages are measured from the local ground potential.

2. The USB OTG FS functionality is ensured down to 2.7 V but not the full USB full speed electrical characteristics which are degraded in the 2.7-to-3.0 V_{DD} voltage range.

3. Guaranteed by design.

4. R_L is the load connected on the USB OTG FS drivers.

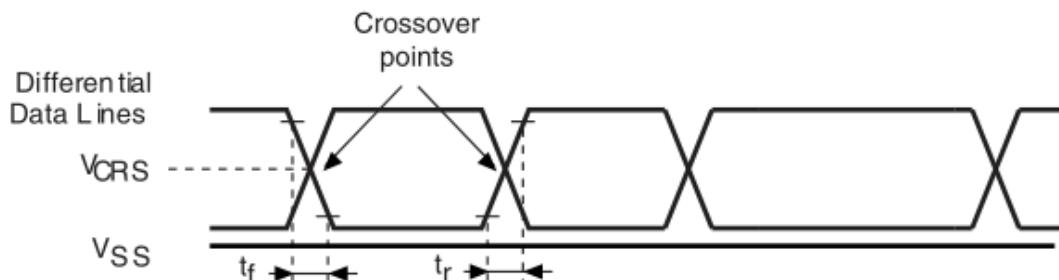


Figure 6-4-1: USB OTG FS timings: definition of data signal rise and fall time

Table 6-4-3: USB OTG FS electrical characteristics ⁽¹⁾

| Driver characteristics | | | | | |
|------------------------|---------------------------------|-----------------------|-----|-----|------|
| Symbol | Parameter | Conditions | Min | Max | Unit |
| t_r | Rise time ⁽²⁾ | $C_L = 50 \text{ pF}$ | 4 | 20 | ns |
| t_f | Fall time ⁽²⁾ | $C_L = 50 \text{ pF}$ | 4 | 20 | ns |
| t_{rfm} | Rise/ fall time matching | t_r/t_f | 90 | 110 | % |
| V_{CRS} | Output signal crossover voltage | | 1.3 | 2.0 | V |

1. Guaranteed by design.

2. Measured from 10% to 90% of the data signal. For more detailed information, please refer to USB Specification - Chapter 7 (version 2.0).

7. RECOMMENDED TEMPERATURE REFLOW PROFILE

The re-flow profiles are illustrated in Figure 4 and Figure 5 below.

- Follow: IPC/JEDEC J-STD-020 C
- Condition:
 - Average ramp-up rate(217°C to peak): $1\sim2^{\circ}\text{C/sec}$ max.
 - Preheat: $150\sim200^{\circ}\text{C}$, $60\sim180$ seconds
 - Temperature maintained above 217°C : $60\sim150$ seconds
 - Time within 5°C of actual peak temperature: $20\sim40$ sec.
 - Peak temperature: $250+0/-5^{\circ}\text{C}$ or $260+0/-5^{\circ}\text{C}$
 - Ramp-down rate: 3°C/sec .max.
 - Time 25°C to peak temperature: 8 minutes max
 - Cycle interval: 5 mintutes

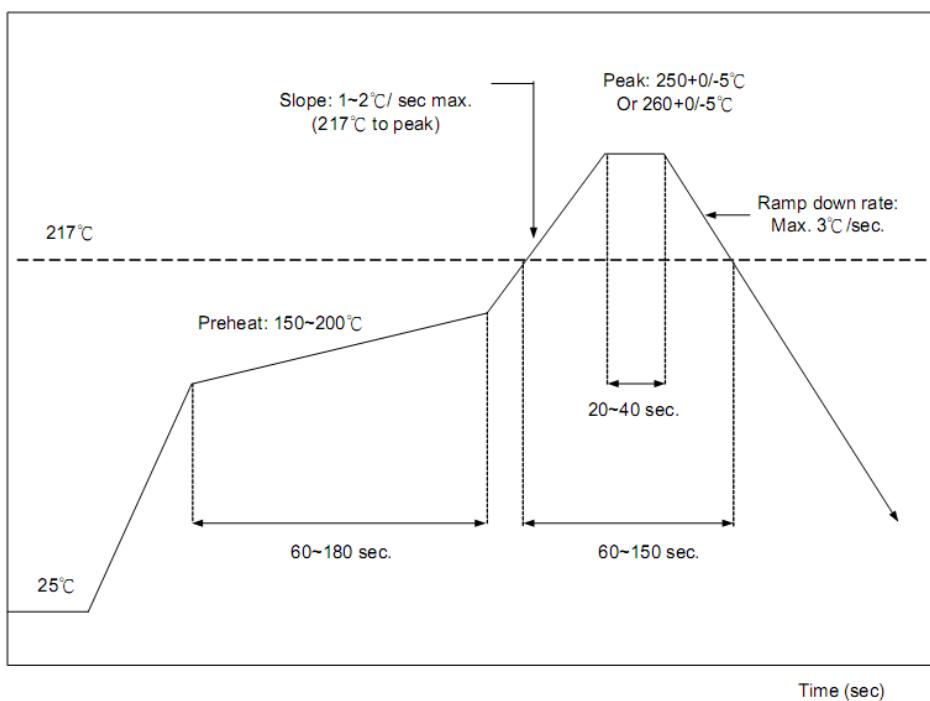


Figure 7-1: Typical Lead-free Re-flow Solder Profile

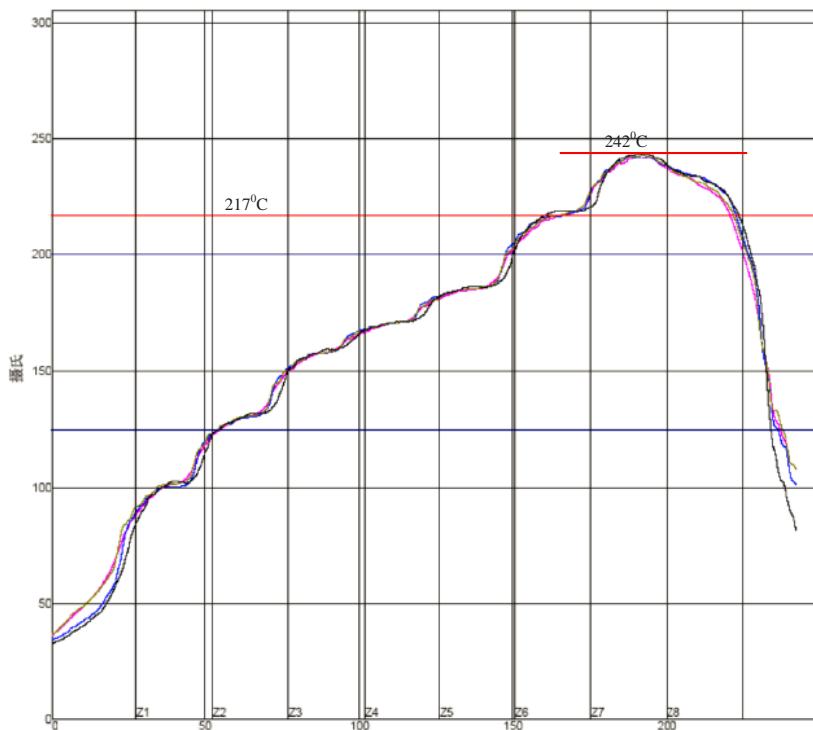


Figure 7-2: Typical Lead-free Re-flow

The soldering profile depends on various parameters according to the use of different solder and material. The data here is given only for guidance on solder re-flow.

FSC-BT909 will withstand up to two re-flows to a maximum temperature of 245°C.

8. Reliability and Environmental Specification

8.1 Temperature test

Put the module in demo board which uses exit power supply, power on the module and connect to mobile. Then put the demo in the -40°C space for 1 hour and then move to +85°C space within 1 minute, after 1 hour move back to -40°C space within 1 minute. This is 1 cycle. The cycles are 32 times and the units have to pass the testing.

8.2 Vibration Test

The module is being tested without package. The displacement requests 1.5mm and sample is vibrated in three directions(X,Y,Z).Vibration frequency set as 0.5G , a sweep rate of 0.1 octave/min from 5Hz to 100Hz last for 90 minutes each direction. Vibration frequency set as 1.5G, a sweep rate of 0.25 octave/min from 100Hz to 500Hz last for 20 minutes each direction.

8.3 Desquamation test

Use clamp to fix the module, measure the pull of the component in the module, make sure the module's soldering is good.

8.4 Drop test

Free fall the module (condition built in a wrapper which can defend ESD) from 150cm height to cement ground, each side twice, total twelve times. The appearance will not be damaged and all functions OK.

8.5 Packaging information

After unpacking, the module should be stored in environment as follows:

Temperature: 25°C ± 2°C

Humidity: <60%

No acidity, sulfur or chlorine environment

The module must be used in four days after unpacking.

9. Layout and Soldering Considerations

9.1 Soldering Recommendations

FSC-BT909 is compatible with industrial standard reflow profile for Pb-free solders. The reflow profile used is dependent on the thermal mass of the entire populated PCB, heat transfer efficiency of the oven and particular type of solder paste used. Consult the datasheet of particular solder paste for profile configurations.

Feasycom will give following recommendations for soldering the module to ensure reliable solder joint and operation of the module after soldering. Since the profile used is process and layout dependent, the optimum profile should be studied case by case. Thus following recommendation should be taken as a starting point guide.

9.2 Layout Guidelines

It is strongly recommended to use good layout practices to ensure proper operation of the module. Placing copper or any metal near antenna deteriorates its operation by having effect on the matching properties. Metal shield around the antenna will prevent the radiation and thus

metal case should not be used with the module. Use grounding vias separated max 3 mm apart at the edge of grounding areas to prevent RF penetrating inside the PCB and causing an unintentional resonator. Use GND vias all around the PCB edges.

The mother board should have no bare conductors or vias in this restricted area, because it is not covered by stop mask print. Also no copper (planes, traces or vias) are allowed in this area, because of mismatching the on-board antenna.

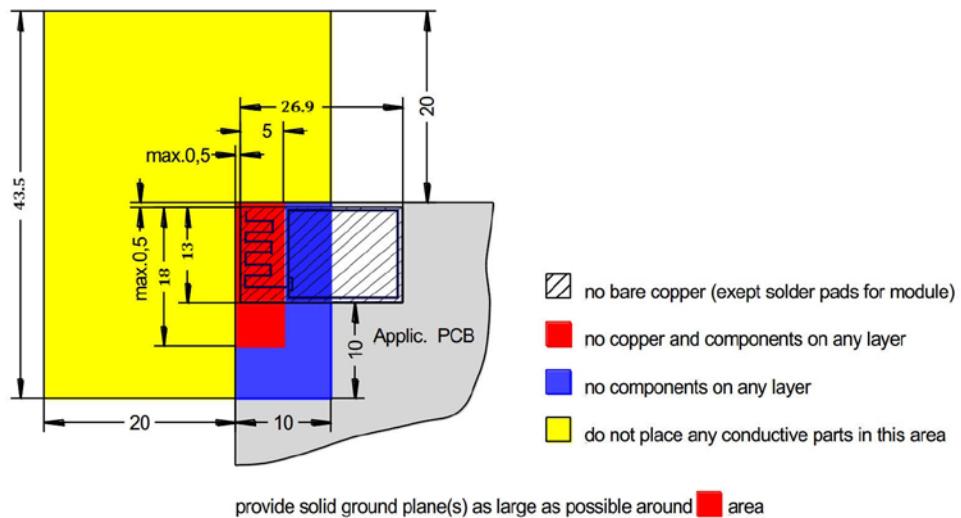


Figure 9-2-1: FSC-BT909 Restricted Area

Following recommendations helps to avoid EMC problems arising in the design. Note that each design is unique and the following list do not consider all basic design rules such as avoiding capacitive coupling between signal lines. Following list is aimed to avoid EMC problems caused by RF part of the module. Use good consideration to avoid problems arising from digital signals in the design.

Ensure that signal lines have return paths as short as possible. For example if a signal goes to an inner layer through a via, always use ground vias around it. Locate them tightly and symmetrically around the signal vias. Routing of any sensitive signals should be done in the inner layers of the PCB. Sensitive traces should have a ground area above and under the line. If this is not possible, make sure that the return path is short by other means (for example using a ground line next to the signal line).

10. Product Packaging Information

10.1 Packing

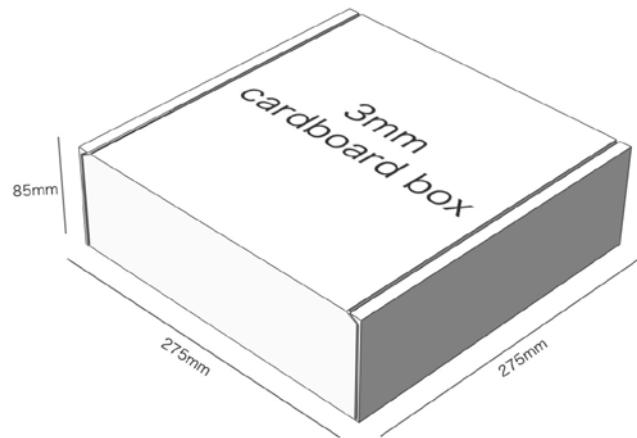
a, Tray vacuum

b, Tray Dimension: 180mm * 195mm



Figure 10-1: Product Packaging Information (Tray)

10.2 Packing box (Optional)



* If require any other packing, must be confirmed with customer

Figure 10-2: Packing Box

11. Certification

11.1 FCC

- ◆ FSC-BT909_FCC Certificate (DSS)

FCC IDENTIFIER: 2AMWOFSC-BT909
Name of Grantee: Shenzhen Feasycom Technology Co.,Ltd
Equipment Class: Part 15 Spread Spectrum Transmitter
Notes: Bluetooth Module

- ◆ FSC-BT909_FCC Certificate (DTS)

FCC IDENTIFIER: 2AMWOFSC-BT909
Name of Grantee: Shenzhen Feasycom Technology Co.,Ltd
Equipment Class: Digital Transmission System
Notes: Bluetooth Module

11.2 CE

- ◆ FSC-BT909_RED_Certificate_BT

EU-RED Certificate of Conformity

Radio Equipment Directive (RED) 2014/53/EU

Registration No. AGC01249170601E0
Manufacturer Shenzhen Feasycom Technology Co.,Ltd
Room 2004A, 20th Floor, Huichao Technology Building,
Jinhai Road, Xixiang, Baoan District, Shenzhen, China
Product Designation Bluetooth Module
Brand Name Feasycom
Model / Series Models FSC-BT909
Factory Shenzhen Feasycom Technology Co.,Ltd
Room 2004A, 20th Floor, Huichao Technology Building,
Jinhai Road, Xixiang, Baoan District, Shenzhen, China

| Requirement | Applied Standards | Document Evidence | Result |
|----------------------|---|--|---------|
| Art.3.1(a) Health | EN 62311:2008 | Test Report: AGC01249170601EH04 | Conform |
| Art.3.1(a) Safety | EN 60950-1:2006+A11:2009 +A1:2010+A12:2011+A2:2013 | Test Report: AGC01249170601ES01 | Conform |
| Art.3.1(b) EMC | Draft EN 301 489-1 V2.2.0 Draft EN 301 489-17 V3.2.0 | Test Report: AGC01249170601EE01 | Conform |
| Art.3.2 Radio | EN 300 328 V2.1.1 | Test Report: AGC01249170601EE04 Test Report: AGC01249170601EE11 | Conform |



Signed by Quality Manager

Issue Date: Aug. 04, 2017

Recognized by Attestation of Global Compliance (Shenzhen) Co., Ltd., in accordance with the RED Directive 2014/53/EU. The certificate doesn't imply assessment of the production. The Applicant of the certificate is authorized to use this certificate in connection with EC declaration of conformity to the Directive. The certificate is only applicable to the equipments described above. This certificate shall not be re-produced except in full without the written approval of Attestation of Global Compliance (Shenzhen) Co., Ltd.

Note: This certificate is part of the full test report(s) and should be used in conjunction with it.



12. Application Schematic